

ABSTRACT

An integrated circuit packaging system, and a method of manufacture of an integrated circuit packaging system thereof, including: an embedding material on a component; a mask layer on the embedding material; a buried pattern in the mask layer, the outer surface of the buried pattern coplanar with the outer surface of the mask layer, the buried pattern electrically connected to the component; a patterned dielectric on a portion of the buried pattern; and an integrated circuit die on the buried pattern.

(Fig.3)